

WHAT IS CLAIMED IS:

1. A system LSI, comprising:
 - a plurality of circuit blocks;
 - a first power supply terminal, which is connected to a first circuit block; and
 - a second power supply terminal, which is connected to a second circuit block, wherein
 - a first level of test voltage is applied from the first power supply terminal to the first circuit block for a predetermined period of time whereby the first circuit block is tested in operation;
 - a second level of test voltage is applied from the second power supply terminal to the second circuit block for a predetermined period of time whereby the second circuit block is tested in operation independently from the first circuit block.
2. A system LSI according to claim 1, wherein
 - the first and second circuit blocks are tested on a wafer before fabrication of the system LSI is completed.
3. A system LSI according to claim 1, wherein
 - the circuit block and power supply terminal are connected to each other one-by-one,
 - the first and second circuit blocks are tested on a wafer before fabrication of the system LSI is completed, and

the first and second supply terminals are connected to a common external terminal after the tests are completed.

4. A system LSI according to claim 3, wherein
the first and second supply terminals are connected to the common external terminal in a wire-bonding process.

5. A system LSI according to claim 1, further comprising:
a third circuit block; and
a switching circuit connected both to the first and second power supply terminals and to the third circuit block, wherein
the switching circuit selectively connects the third circuit block to the first and second power supply terminals whereby the third circuit block is tested efficiently.

6. A system LSI according to claim 5, wherein
the first, second and third circuit blocks are tested on a wafer before fabrication of the system LSI is completed.

7. A system LSI according to claim 5, wherein
the circuit blocks and power supply terminals are connected to each other one-by-one,
the first, second and third circuit blocks are tested on a wafer before fabrication of the system LSI is completed, and
the first, second and third supply terminals are connected to a

common external terminal after the tests are completed.

8. A system LSI according to claim 5, wherein
the first, second third supply terminals are connected to the
common external terminal in a wire-bonding process.